

X32陶瓷系列/X32 Glass Series

CHX32GB-16.000M112B2-NT

(料号参考下页选型指南)

Exempted by RoHS



※ 应用及特点 Application & Features

- 电脑、网卡、通讯 Computer, Modem, Communications
- 蓝牙、无线 Bluetooth, Wireless
- 自动控制设备及其它 Automotive Equipment at Other
- 陶瓷封装尺寸: 3.2×2.5×0.8mm Glass Package

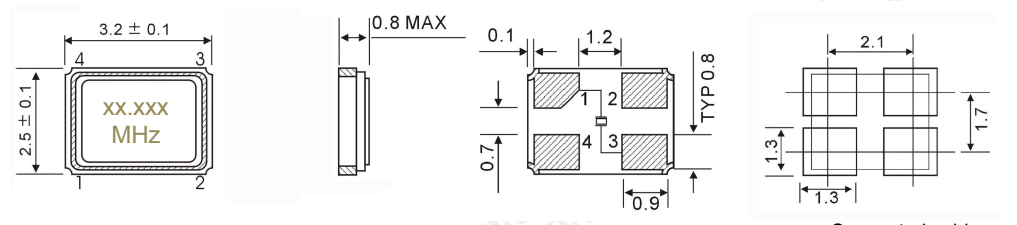
※ 电气参数 Electrical Specification

项目 Item	参数 Parameter
频率范围 Frequency Range	8.000 to 50.000MHz
调整频差 Frequency Tolerance) (ΔF)(at25°C)	± 10 to ± 50 ppm
温度频差 Frequency Drift)	± 10 to ± 50 ppm
工作温度 Operating Temperature Range	-20 to 70 / -40 to 85 °C
储存温度 Storage Temperature Range	-40 to 85 °C
负载电容 Load Capacitance , (CL)	Suggested by customer(6-50PF/或串联)
激励功率 Drive Level)	10 μ W to 100 μ W
静态电容 Shunt Capacitance ,(C0)	7.0pF Max
老化率 Aging at 25 °C	± 5 ppm/year Max
绝缘阻抗 Insulation Resistance (Rs)	500M Ω Min at100Vdc

※ 等效电阻和振荡模式 Equivalent Series Resistance (ESR) and Mode of Oscillation

频率范围 Frequency Range (MHz)	等效阻抗 ESR(Ω)	振荡模式 Mode of Oscillation
8.000 - 20.000 MHz	100 Max	基频 AT Fund
20.000 - 30.000 MHz	80 Max	基频 AT Fund
30.000 - 40.000 MHz	60 Max	基频 AT Fund
40.000 - 50.000 MHz	40 Max	基频 AT Fund

※ 外形尺寸及印字 Mechanical Dimensions and Marking



Top view dimensions: 3.2 ± 0.1 mm (width), 2.5 ± 0.1 mm (height), 4 mm (total width including pads), 3 mm (total height including pads). Marking: XX.XXX MHz.

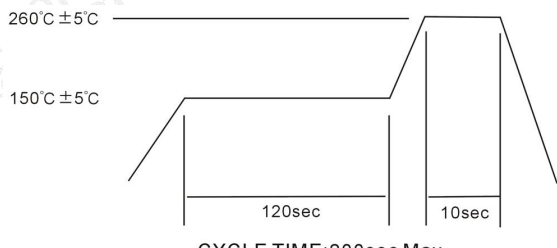
Side view dimensions: 0.8 MAX mm (height), 0.1 mm (top pad thickness), 0.7 mm (bottom pad thickness), 1.2 mm (pad width), 0.9 mm (pad spacing), TYP 0.8 mm (package thickness).

Cross-sectional view dimensions: 2.1 mm (total width), 1.3 mm (pad width), 1.7 mm (pad height).

UNIT(单位):mm(毫米)	
#1	输入
#3	输出
#2、4	接地

Suggested solder pad layout 推荐焊盘

※ 应用环境标准 Environmental /Mechanical SPEC

项目 Item	参数 Parameter	回流焊条件 Reflow Condition
耐冲击性 Shock Resistance	跌落测试:75cm 高度,跌落三次至硬木板 Drop from Height 75cm to hard wooded board 3 times	 <p>CYCLE TIME:200sec Max.</p>
焊接条件 Solder Condition	引线焊接时,烙铁最高温度 260 度,焊接时间最长 10 秒 Lead wire should be soldered with 10S with the iron heated to a tip temperature 260°C (Max)	

※ 选型指南 Part Number Guide

CH	X32GB	16.000M	1	12	B2	-	N	T
CHXTAL	型号 Table1	频率 Frequency Range	振荡模式 1: Fund 3: 3RD 5: 5thovertone	负载电容(PF) Load Capacitance	包装方式 B: 散包 Bulk T: 编带 Tape	附加加工 N: 普通 Normal C: 切脚 Lead Cutting G: 弯脚 Gull Wing J: 套管 Jacket I: 绝缘垫片 Insulator	温度特性 Table2	

※ Table1 型号/Type

A	B	C	D	E	F	G	H
X11SB	X21SB	X22SB	X32SB	X32GB	X53SB	X53SA	X53GA

※ Table2 温度特性及频差/Frequency stability at Temperature Range

温度特性及频差 Frequency stability @Temperature Range							
	Temp (°C)	-10~60	-20~70	-40~85	-40~105	-40~125	-55~125
Stability (ppm)		A	B	C	D	E	F
±10	1	*	*				
±20	2	*	*	*			
±30	3	*	*	*			
±50	5	*	*	*			